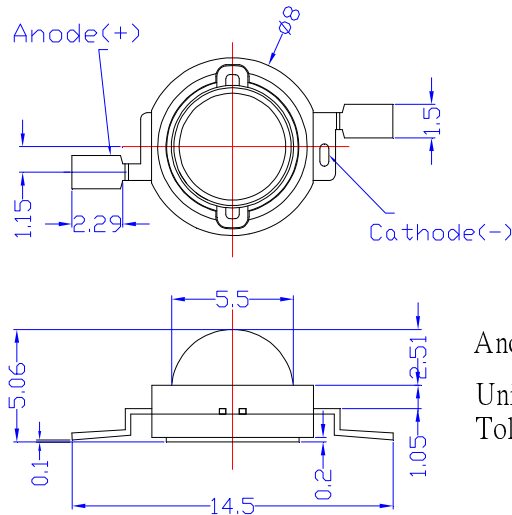


■Features

- Highest luminous flux
- Super energy efficiency
- Very long operating life
- Superior ESD protection

■Outline Dimension



Anode —> Cathode

Unit:mm

Tolerance:±0.30mm

■Applications

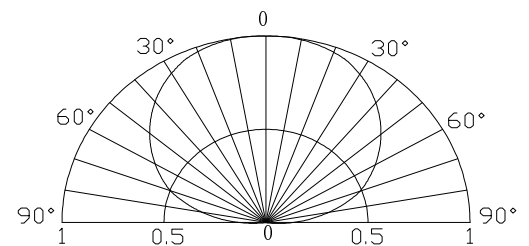
- Night Vision
- Camera
- Outdoor./Indoor applications

■Absolute Maximum Rating

(Ta=25°C)

Item	Symbol	Value	Unit
DC Forward Current	I_F	1000	mA
Pulse Forward Current*	I_{FP}	2000	mA
Reverse Voltage	V_R	5	V
Power Dissipation	P_D	2000	mW
Operating Temperature	T_{opr}	-30 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +100	°C
Lead Soldering Temperature	T_{sol}	260°C/5sec	-

■Directivity



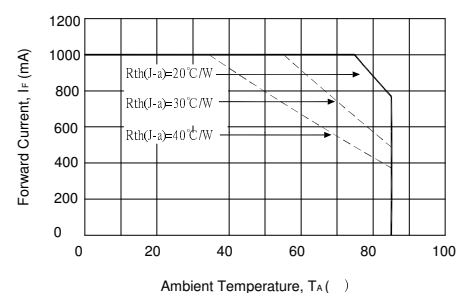
*Pulse width Max.10ms Duty ratio max 1/10

■Electrical -Optical Characteristics

(Ta=25°C)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
DC Forward Voltage	V_F	$I_F=700mA$	-	1.7	2.0	V
DC Reverse Current	I_R	$V_R=5V$	-	-	10	μA
Peak Wavelength	λ_p	$I_F=700mA$	-	850	-	nm
Radiant Power	P_O	$I_F=700mA$	200	250	-	mW
50% Power Angle	$2\theta_{1/2}$	$I_F=700mA$	-	140	-	deg

■Forward Operating Current (DC)



Note: Don't drive at rated current more than 5s without heat sink for Xeon 3 emitter series.

■ **Soldering Heat Reliability :**

Reflow soldering Profile

- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the **characteristics of the LEDs will or will not be damaged by repairing.**

Solder
Average ramp-up rate = 3°C/sec. max.
Preheat temperature: 150°~180°C
Preheat time = 120 sec. max.
Ramp-down rate = 6°C/sec. max.
Peak temperature = 220°C max.
Time within 3°C of actual peak temperature = 25 sec. max.
Duration above 200°C is 40 sec. max.

